



Material Content Data Sheet



Sales Product Name	TLE75004-EPD			Issued	1. August 2018			
MA#	MA001682898							
Package	PG-TSDSO-14-41			Weight*	64.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.299	2.00	2.00	20030	20030
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		144	
	non noble metal	zinc	7440-66-6	0.037	0.06		574	
	non noble metal	iron	7439-89-6	0.745	1.15		11488	
wire	non noble metal	copper	7440-50-8	30.247	46.65	47.87	466475	478681
	non noble metal	copper	7440-50-8	0.497	0.77	0.77	7669	7669
	encapsulation	organic material	carbon black	1333-86-4	0.087	0.13		1337
encapsulation	plastics	epoxy resin	-	3.382	5.22		52155	
	inorganic material	silicondioxide	60676-86-0	25.436	39.23	44.58	392280	445772
leadfinish	non noble metal	tin	7440-31-5	1.642	2.53	2.53	25318	25318
plating	noble metal	silver	7440-22-4	0.823	1.27	1.27	12686	12686
glue	plastics	epoxy resin	-	0.112	0.17		1723	
	noble metal	silver	7440-22-4	0.527	0.81	0.98	8121	9844
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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